

HEADERS & RECEPTACLES





✓ Active

<u>±</u>

PRODUCT DRAWING



3D PDF

TE CONNECTIVITY (TE)

04 MTE HDR SRST LATCH W/HLDWN

AMPMODU | AMPMODU MTE

104809-3

TE Internal Number: 104809-3

Not EU RoHS or ELV Compliant Find Compliant Alternatives

Centerline 2.54 mm [.1 in]

Number of Positions 4

PCB Mounting Orientation Vertical

PCB Mounting Style Through Hole (SMT Compatible)

Number of Rows 1

Product Drawings

PLZD HDR ASSY, AMPMODU MTE, VERTICAL SINGLE ROW, 2.54[.100] CL,

0.64[.025] SQ POSTS, WITH LATCHING & HOLD DOWN

PDF **English**

CAD Files

Customer View Model

2D_DXF.ZIP **English**

Customer View Model

3D_IGS.ZIP **English**

Customer View Model

3D_STP.ZIP **English**

3D PDF

PDF **English**

Catalog Pages/Data Sheets

AMPMODU_MTE_INTERCONNECT_SYSTEM_QRG_4-1773458-0

PDF **English**

Product Specifications

Application Specification AMPMODU MTE Interconnection System

PDF **English**

Please review product documents or contact us for the latest agency approval information. Please Note: Use the Product Drawing for all design activity.

Product Type Features

PCB Mounting Orientation

Vertical

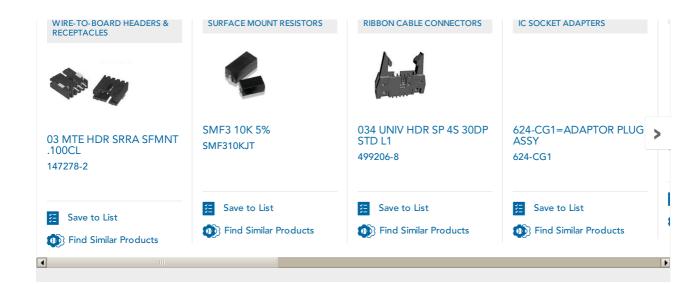
Product Type

Connector

Strain Relief Row-to-Row Spacing Connector Style Ping PCS Orientation Feature Applies To Printed Circuit Board Configuration Features Number of Positions Anumber of Rows Backwall/Post Interruptions Without Delectrical Characteristics Delectric Withstanding Voltage Insulation Resistance Insulation Resistance Sooo Min Termination Resistance Tortact Mating Area Plating Material Contact Mating Area Plating Thickness (ain) Contact Termination Area Plating Material Tal Plating Material Tal Plating Material Tal Plating Material Tin-Lead Tal Plating Material Tal Plating Thickness Contact Tal Tin-Lead Tal Plating Thickness Contact Termination Area Plating Material Tin-Lead Tal Plating Thickness Contact Tal Plating Material Tin-Lead Tal Plating Thickness Contact Tal Plating Material Tin-Lead Tal Contact Tal Contact Plating Material Tin-Lead Tal Contact Tal Contact Plating Material Tin-Lead Tal Contact Tal Contact Plating Material Tin-Lead Contact Current Rating (A) Contact Termination Area Plating Material Tin-Lead Tin-L		Connector Type	Header
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Mechanical Attachment PCB Mounting Style Through Hole (SMT Compatible) PCB Mount Alignment Without Mating Retention With		Contact Base Material	Brass
PCB Mount Alignment Without Mating Retention With	Termination Features	Termination Method to Wire/Cable	Crimp, Insulation Displacement Crimp (IDC)
Mating Retention With	Mechanical Attachment	PCB Mounting Style	Through Hole (SMT Compatible)
		PCB Mount Alignment	Without
PCB Mount Retention With		Mating Retention	With
		PCB Mount Retention	With

	PCB Mount Retention Type	Hold-Down
	Contact Retention	With
	Mating Alignment Type	Latched
	Contact Retention Type	Locking Lance
	Mating Retention Type	Hold-Down
	Mating Alignment	With
Housing Features	Centerline	2.54 mm [.1 in]
	Housing Color	Black
	Housing Material	Thermoplastic
Dimensions	Tail Length	3.3 mm [.13 in]
	Mating Post Length	5.84 mm [.23 in]
	PCB Thickness (Recommended)	1.58 mm [.062 in]
	Height	13.59 mm [.535 in]
	Length	12.7 mm [.5 in]
Usage Conditions	Temperature Rating	High
	Operating Temperature Range (°C)	-65 – 105
Operation/Application	For Use With	Receptacle Housing Assembly
		Receptacie Housing Assembly
	Pick and Place Cover	Without
Industry Standards	Pick and Place Cover UL Flammability Rating	
Industry Standards		Without
Industry Standards Packaging Features	UL Flammability Rating	Without UL 94V-0
	UL Flammability Rating Approved Standards	UL 94V-0 CSA LR7189, UL E28476
	UL Flammability Rating Approved Standards Packaging Method	Without UL 94V-0 CSA LR7189, UL E28476 Tube, Tube/Box

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